

#5/Prel. Amendment A
D. Dillon
3-21-02

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Application No.: New Rule 1.53(b) Continuation of Application No. 09/589,353

Filed: November 26, 2001

Docket No.: 103092.02

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING
THE SAME, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 11, lines 13-14, delete current paragraph and insert therefor:

#1
Fig. 1A is a cross-sectional view of a first embodiment of the semiconductor device;
and Fig. 1B is an enlarged view of the encircled portion of Fig. 1A.

Page 12, lines 18-27, delete current paragraph and insert therefor:

A2
Fig. 1A shows a first embodiment of the semiconductor device. A semiconductor device 10 comprises a semiconductor chip 12, being an example of a semiconductor chip, and an insulating film 14, being an example of a substrate, to which the CSP type of package is applied. On the insulating film 14 are formed external electrodes 16, and the semiconductor chip 12 has a plurality of electrodes 13. In Fig. 1A, the electrodes 13 are formed on only two opposite sides of the semiconductor chip 12, but as is well known, may equally be formed on four sides.